

## IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A method of manufacturing an electronic part in which that side of an insulating member sandwiched between conductor film and a lower conductor layer which is adjacent to said conductor film, conductor portions connected from said lower conductor layer are exposed, comprising

forming a plurality of opening portions each having said lower conductor layer as bottoms in the formed area of said conductor portions from said conductor film side,

growing metal plating layers from each of the bottoms of said opening portion with said lower conductor layer as an electrode,

growing metal plating layers on the upper surfaces of said conductor film and said conductor portions with said conductor film and said conductor portions as electrodes after said conductor portions are formed to the substantial same height in the respective plurality of opening portions by growing said metal plating layers so as to contact said metal plating layers with said conductor film and to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening portions, and forming a thickness enough to form an upper conductor layer.

Claim 2 (Original): A method of manufacturing an electronic part in which on the upper surface of an insulating member covering a lower conductor layer, conductor portions connected from said lower conductor layer are exposed, comprising

forming conductor film on the upper surface of said insulating member and protective film formed on a part of the upper surface of said insulating member and protective film in a thickness direction, and thereafter forming a plurality of opening portions each having said

lower conductor layer as a bottom in said protective film and said conductor film in the formed area of said conductor portion,

growing metal plating layers from the bottoms of said plurality of opening portions with said lower conductor layer as an electrode, and

growing metal plating on the upper surfaces of said conductor film and said conductor portions with said exposed conductor film and said conductor portions on which protective film is not formed as electrodes, to thereby form a thickness enough to form an upper conductor layer after said conductor portions are formed to the substantial same height in the respective plurality of opening portions by growing said metal plating layers so as to contact said metal plating layers with said conductor film and to lower growing speed of said metal plating layers, to thereby form said conductor portions in said opening portions.

Claim 3 (Currently Amended): A method according to Claim 1 ~~or~~ 2, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 4 (Currently Amended): A method according to Claim 1 ~~or~~ 2, wherein said insulating member and said conductor film are made integral with each other in advance.

Claim 5 (New): A method according to Claim 2, wherein said exposed conductor film providing said electrode is set outside a product area.

Claim 6 (New): A method according to Claim 2, wherein said insulating member and said conductor film are made integral with each other in advance.